reliability evaluation of product wafers, said method comprising:

providing a magnetic circuit for magnetically inducing said voltage for applying to said at least one chip for the probing thereof in the absence of physically contacting the chip surface; and

a mask being interposed on said wafer for magnetically inducing said voltage to said at least one chip, said mask having the voltage induced thereto and thereafter conducted to electrical contacts on said wafer.

2. (Amended) A method as claimed in Claim 1, wherein said magnetically induced voltage is produced for a circuit utilizing a time varying magnetic field which is fixed with respect to said circuit.

4. (Amended) A method as claimed in Claim 1, wherein said mask which contains said circuit is positioned on said wafer; and connections are made to said at least one chip by said mask for effectuating said burn-in without interference with the normal operation of said at least one semiconductor chip.

5. (Amended) A method as claimed in Claim 2, wherein said magnetic circuit comprises a loop defining an area on said wafer, said mask being positioned on said wafer so as to enclose said area and having electrical contacts for an induced voltage through said time varying magnetic field within said enclosed area.

10. (Amended) A method as claimed in Claim 2, wherein said magnetic field is produced by a magnetic system which comprises a circular magnetic core having an air gap for receiving said wafer with said at least one chip and said mask positioned thereon; and a voltage source connected to an electrical coil for energizing said magnetic core to produce said induced voltage.

13

11. (Amended) A method as claimed in Claim 10, wherein said said magnetic core is energized through a radio frequency voltage source.

26. (Amended) A system for electrically stressing through a specified voltage at least one semiconductor chip on a wafer for controlled contactless burn-in, voltage screen and reliability evaluation of product wafers, said system comprising:

an arrangement (a circuit) for applying said voltage to said at least one chip for the probing thereof in the absence of physically contacting the chip surface; and

14

a mask being arranged on said wafer through which said voltage is magnetically induced and applied to said at least one chip through the interposition of said mask onto which the voltage is induced and thereafter conducted to electrical contacts on said wafer.

27. (Amended) A system as claimed in Claim 26, wherein said induced voltage is produced for a circuit by utilizing a time varying magnetic field which is fixed with respect to said circuit.

30. (Amended) A system as claimed in Claim 27, wherein said circuit comprises a loop defining an area on a wafer, said mask being positioned on said wafer so as to enclose said area; and a loop having electrical contacts for an induced voltage through said time varying magnetic field being provided within said enclosed area.

35. (Amended) A system as claimed in Claim 28, wherein said magnetic field is produced by a magnetic system which comprises a circular magnetic core having an air gap for receiving said wafer with said at least one chip and said mask positioned thereon; and an electrical coil for energizing said magnetic core to produce said induced voltage.

36. (Amended) A system as claimed in Claim 35, wherein said electrical core is energized through a radio frequency voltage source.

REMARKS

Careful consideration has been given by applicants to the Examiner's comments and rejection of the various of the claims as set forth in the outstanding Office Action and favorable reconsideration and allowance of the application, as amended is earnestly solicited.

Applicants note the Examiner's withdrawal of Claims 17 - 20, and 42 - 46 as being drawn to a non-elected species, and no consideration is being given to those claims at this time.

Concerning the rejection of Claims 1 - 16, 21 - 41 and 47 - 50 under 35 U.S.C. 112, second paragraph for utilizing indefinite terminology, applicants have amended the claims, as applicable, to provide appropriate terminology in conformance with the U.S. practice and also providing the necessary explanatory subject matter. Consequently, applicants respectfully